

Title (en)  
ELECTRONICS CIRCUIT MANUFACTURE

Title (de)  
HERSTELLUNG ELEKTRONISCHER SCHALTUNG

Title (fr)  
FABRICATION DE CIRCUITS ELECTRONIQUES

Publication  
**EP 1514307 A1 20050316 (EN)**

Application  
**EP 03760849 A 20030619**

Priority  
• IE 0300094 W 20030619  
• IE 20020503 A 20020722  
• IE 20030455 A 20030619

Abstract (en)  
[origin: WO2004001848A1] A circuit with embedding components (13) is produced by placing the components (13) on a substrate (14) and applying sheets (15) of prepreg. The prepreg sheets (15) have apertures to accommodate the -components, the number of sheets and arrangement of apertures being chosen to accommodate a variety of component X, Y and Z dimensions. A top layer with Cu foil (16(b)) is applied. The assembly is pressed in an operation analogous to conventional multilayer board lamination pressing. This causes all of the prepreg resin to flow to completely embed the components without raids or damage. Electrical connections are made by drilling and plating vias.

IPC 1-7  
**H01L 23/538**

IPC 8 full level  
**H01L 23/538** (2006.01); **H05K 1/18** (2006.01); **H01L 21/60** (2006.01); **H01L 21/98** (2006.01); **H01L 23/367** (2006.01); **H01L 25/065** (2006.01)

CPC (source: EP)  
**H01L 23/5389** (2013.01); **H01L 24/19** (2013.01); **H01L 24/20** (2013.01); **H01L 24/82** (2013.01); **H05K 1/185** (2013.01); **H01L 23/3677** (2013.01); **H01L 24/81** (2013.01); **H01L 25/0657** (2013.01); **H01L 25/50** (2013.01); **H01L 2224/04105** (2013.01); **H01L 2224/73267** (2013.01); **H01L 2224/81801** (2013.01); **H01L 2224/82** (2013.01); **H01L 2224/82039** (2013.01); **H01L 2224/85** (2013.01); **H01L 2224/86** (2013.01); **H01L 2224/92144** (2013.01); **H01L 2924/01005** (2013.01); **H01L 2924/01006** (2013.01); **H01L 2924/01013** (2013.01); **H01L 2924/01029** (2013.01); **H01L 2924/01033** (2013.01); **H01L 2924/01039** (2013.01); **H01L 2924/01061** (2013.01); **H01L 2924/01075** (2013.01); **H01L 2924/01078** (2013.01); **H01L 2924/01079** (2013.01); **H01L 2924/01082** (2013.01); **H01L 2924/014** (2013.01); **H01L 2924/10253** (2013.01); **H01L 2924/12042** (2013.01); **H01L 2924/14** (2013.01); **H01L 2924/19041** (2013.01); **H01L 2924/19043** (2013.01); **H01L 2924/19105** (2013.01); **H01L 2924/3025** (2013.01); **H01L 2924/3512** (2013.01); **H05K 1/0206** (2013.01)

Citation (search report)  
See references of WO 2004001848A1

Designated contracting state (EPC)  
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PT RO SE SI SK TR

DOCDB simple family (publication)  
**WO 2004001848 A1 20031231**; AU 2003253227 A1 20040106; EP 1514307 A1 20050316; IE 20030455 A1 20031231

DOCDB simple family (application)  
**IE 0300094 W 20030619**; AU 2003253227 A 20030619; EP 03760849 A 20030619; IE 20030455 A 20030619